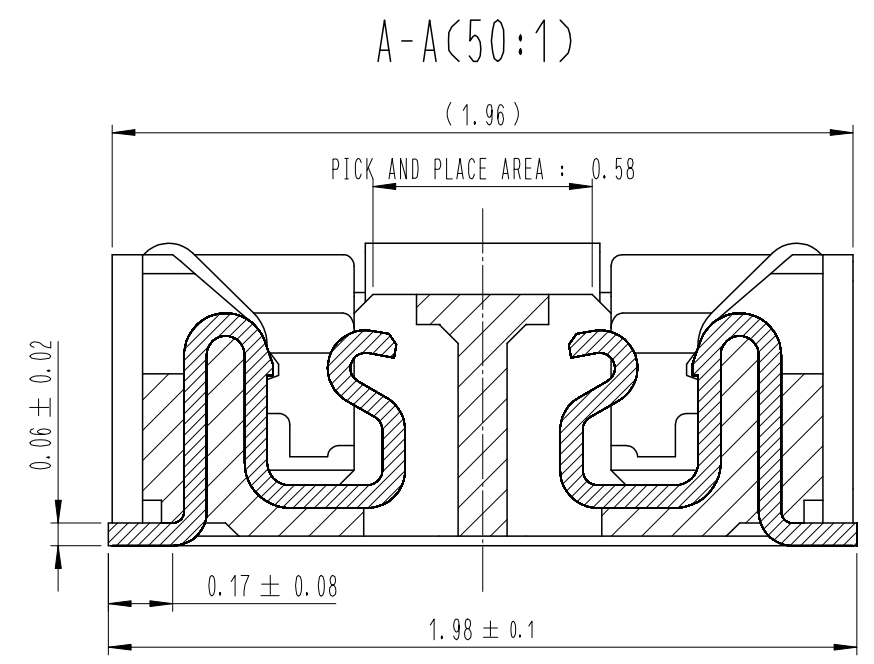


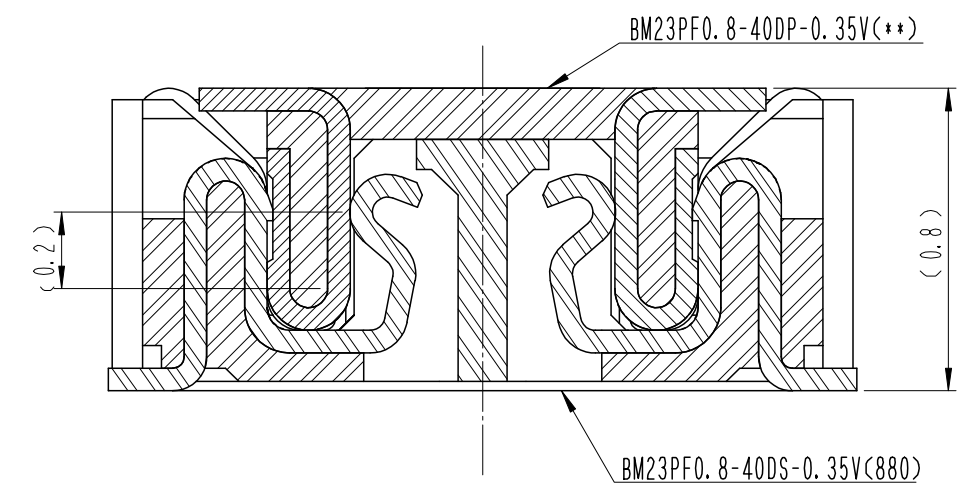
DRAWING FOR REFERENCE
This is subject to change without notice

- NOTE
- 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX.
 - 2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μm MIN.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 3. METAL FITTING PLATING SPECIFICATIONS.
SMT LEAD : GOLD 0.05 μm MIN.
UNDERPLATING : NICKEL 1 μm MIN.
(SURFACE : SEALING)
 - 4. HRS MARK AND CAV NO. IS INDICATED IN APPROX POSITION SHOWN.

△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B	檢圖 Y	年月日 DATE	△數 COUNT	訂正事項 DESCRIPTION OF REVISIONS	擔當 B	檢圖 Y	年月日 DATE
△					△				
△					△				
△					△				



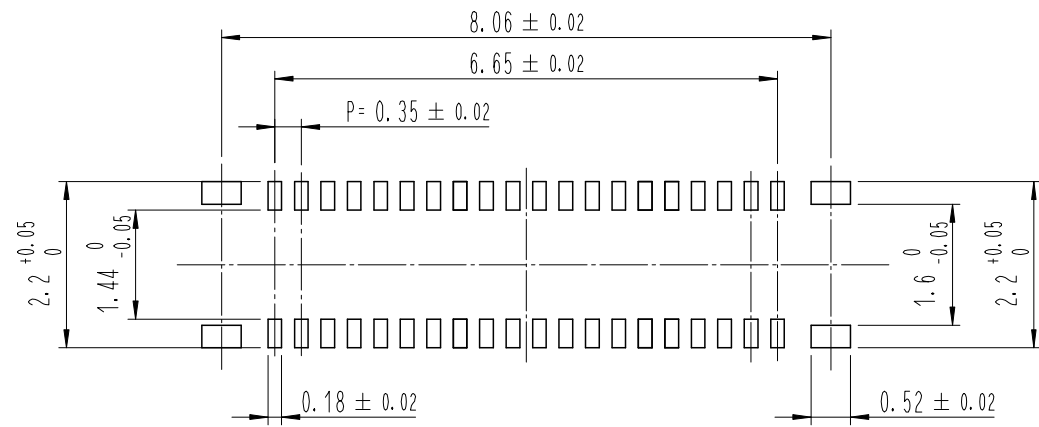
ENGAGEMENT FIGURE (50:1)



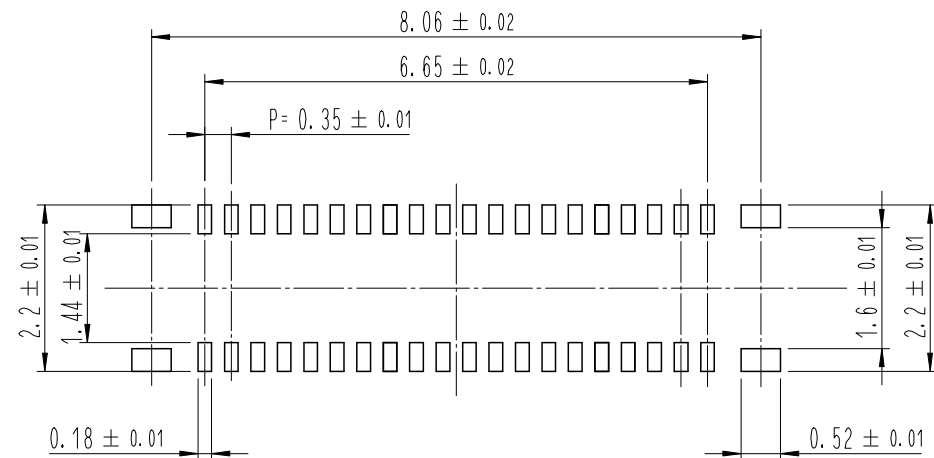
4	PS	CLEAR (EMBOSSD CARRIER TAPE)							
3	△ COOPER ALLOY	3							
2	△ COOPER ALLOY	2	6	PS		BLACK (PLASTIC REEL)			
1	LCP	UL94 V-0, BLACK	5	POLYESTER		CLEAR (COVER TAPE)			
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL		FINISH, REMARKS			
REMARKS				DRAWN	DESIGNED	CHECKED	APPROVED	RELEASED	
				Y. J. LEE	Y. J. LEE	H. W. JO	T. S. KANG	17.06.08	
				17.06.08	17.06.08	17.06.08	17.06.08		
CODE NO. (OLD)	SCALE	DRAWING NO.	PART NO.						
	10:1	EDC3-*****	BM23PF0.8-40DS-0.35V(880)						
	UNITS	HRS HIROSE KOREA CO., LTD.	CODE NO	CL 66*-*****-880			1/3		
	mm								

A
B
C
D
E
F

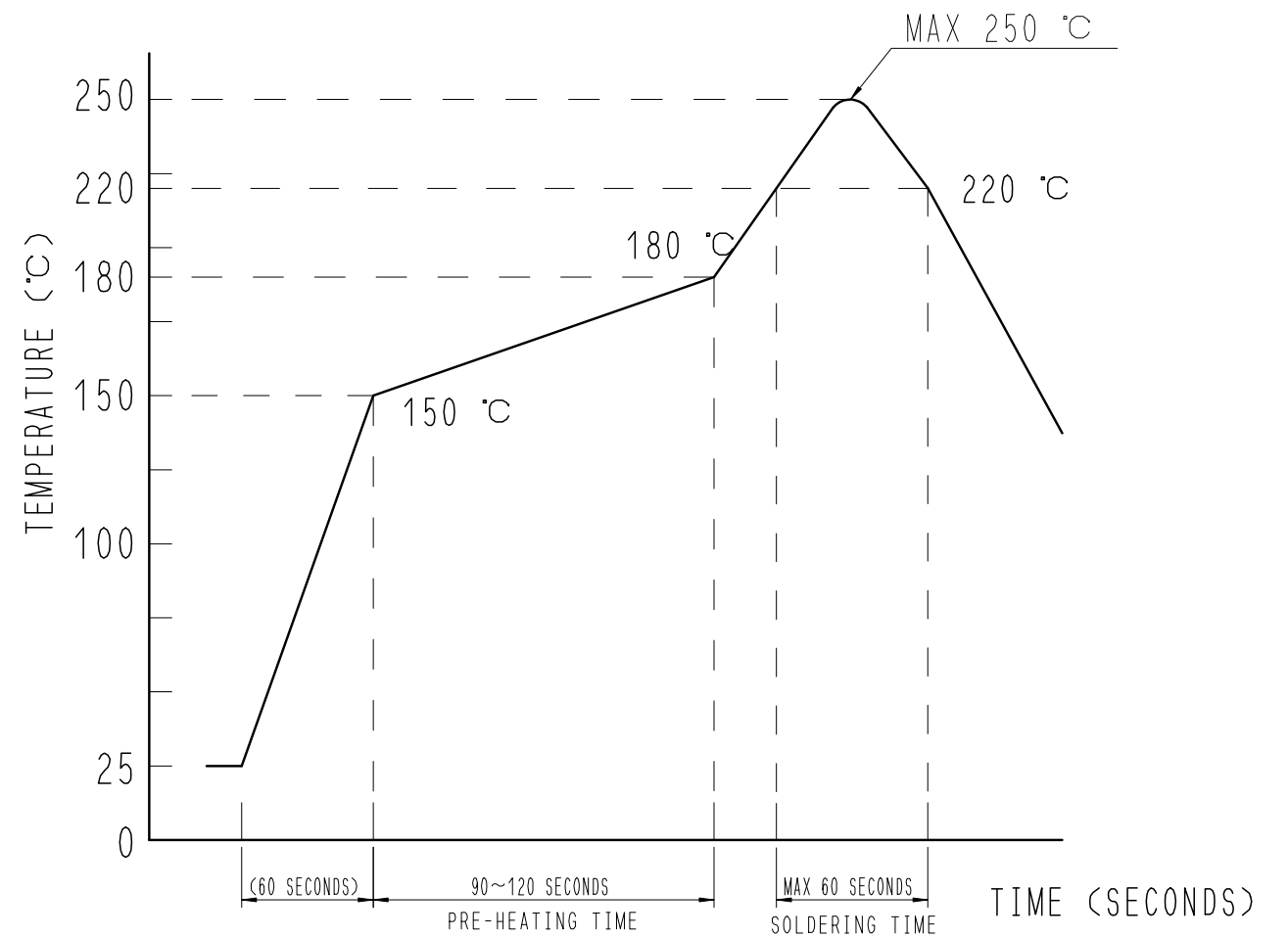
6 RECOMMENDED PCB LAYOUT



RECOMMENDED METAL MASK DIMENSIONS
MATAL MASK THICKNESS : 100 μm



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: N₂ REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
 1) REFLOW TIME
 DURATION ABOVE 220°C: 60 SEC MAX.
 (PEAK TEMPERATURE: 250°C MAX)
 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE (MIN): 150°C
 PRE-HEAT TEMPERATURE (MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

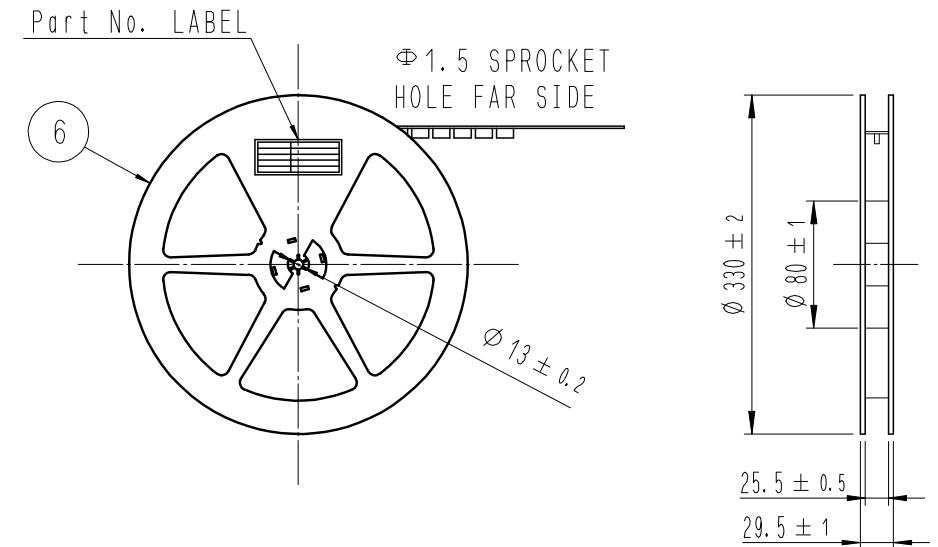
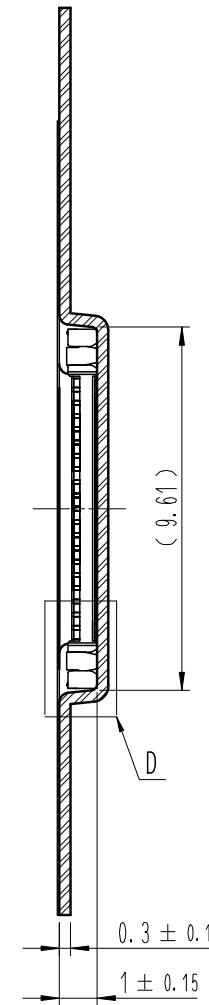
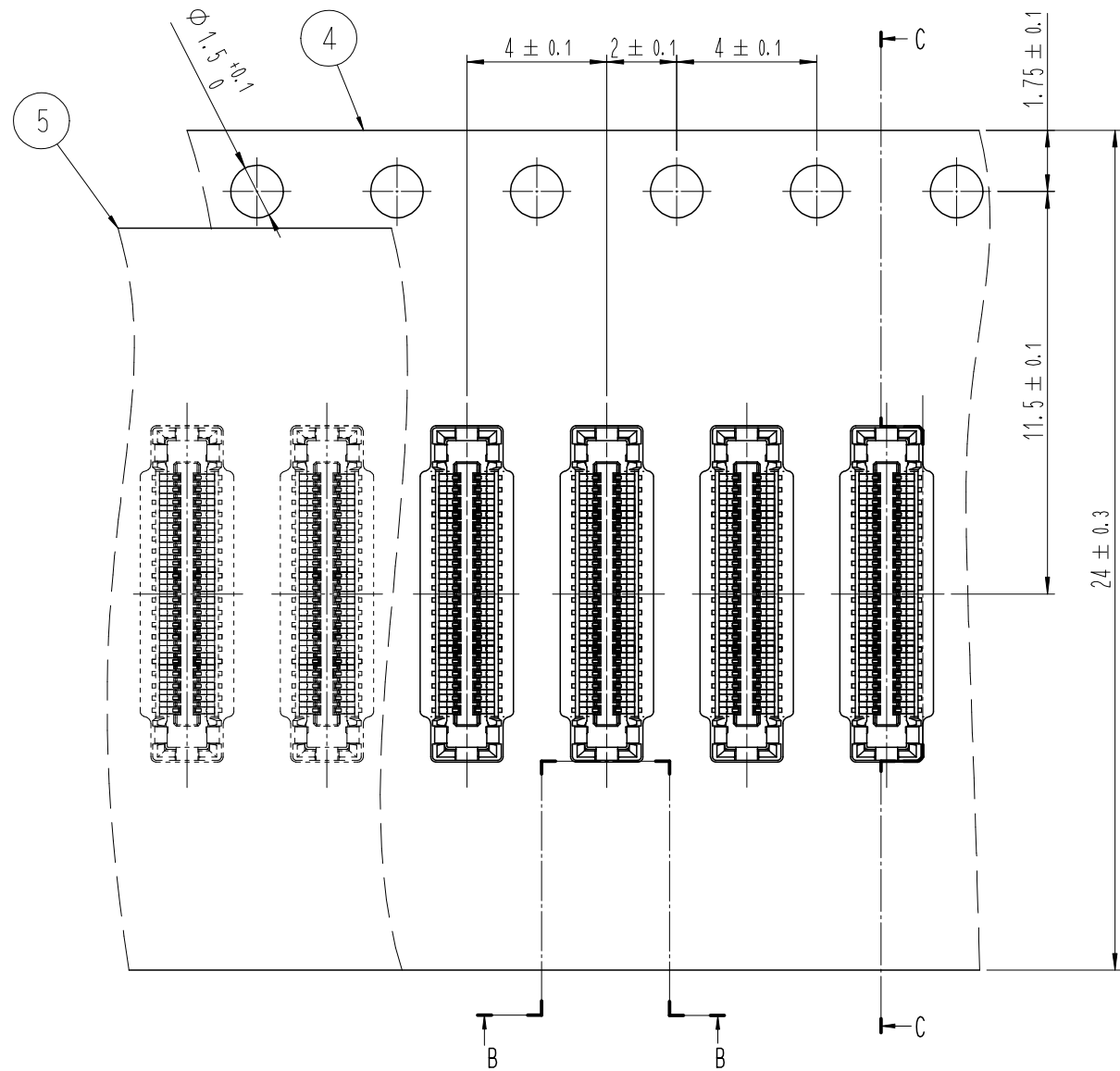
- 5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.
- 6 PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

	DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-40DS-0.35V(880)
	SCALE	10:1	CODE NO	CL 66*-*****-880
UNITS	mm	HRS HIROSE KOREA CO., LTD.		2/3

EMBOSSED CARRIER TAPE PACKAGING (5:1)

C-C (5:1)

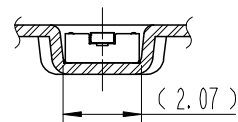
STYLE AND DIMENTION OF REEL (FREE)



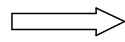
DETAIL OF PART NO. LABEL

SUPPLIER	
QUANTITY	
PART NO.	
CODE NO.	
DATE OF MANUFACTURED	
生産月日	年 月 日
図番	** ** *
品名	BM23PF0.8-40DS-0.35V(880)
納入数量	10,000個
納入者	HIROSE KOREA

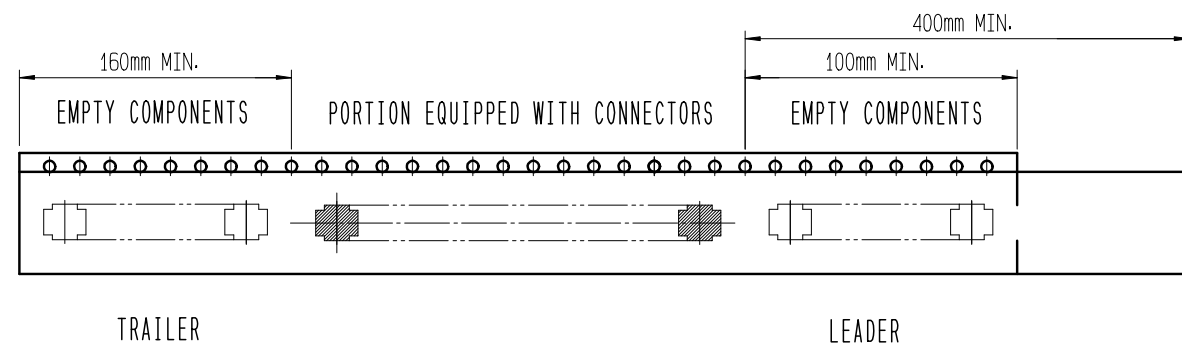
B-B (5:1)



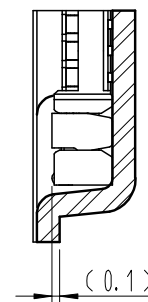
DIRECTION OF UNREELING



10 TAPING(FREE)



D (10:1)



- 7 . PER REEL 10,000 CONNECTORS.
- 8 . THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.
- 9 > REFER TO JIS C 0806. IEC-60286-3 (PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)

SCALE 10:1	DRAWING NO.	EDC3-*****	PART NO.	BM23PF0.8-40DS-0.35V(880)
	UNITS mm	HRS HIROSE KOREA CO.,LTD.		CODE NO CL 66**-*****-880